

# 2021 ECTC Sponsorship Opportunities

Wolfgang Sauter  
ECTC Sponsorship Chair  
wsauter2@gmail.com

# Sponsorship Tiers – the 10,000 Foot View

## Platinum Sponsor

\$10,000

Limited to only 3 sponsors, this top level sponsorship puts your company logo on the front door and every page of ECTC. This is the right choice if you want your company name recognized as a very select top contributor.

## Gold Sponsor

\$7,500

Limited to only 5 sponsors, this sponsorship provides your company exposure on every page of the entire conference. This is the right choice if you want your company name to be seen as widely as possible.

## Panel Sponsor

\$5,000

This sponsorship makes you the hosting partner for one of the 10 high-demand live sessions. This is the right choice if the panel reflects your company goals and/or you have a panelist on the panel.

## Session Sponsor

\$2,500

This entry level sponsorship makes you the hosting partner for one of the 46 on-demand technical sessions that make ECTC the premier packaging conference.

## Exhibitor Combo

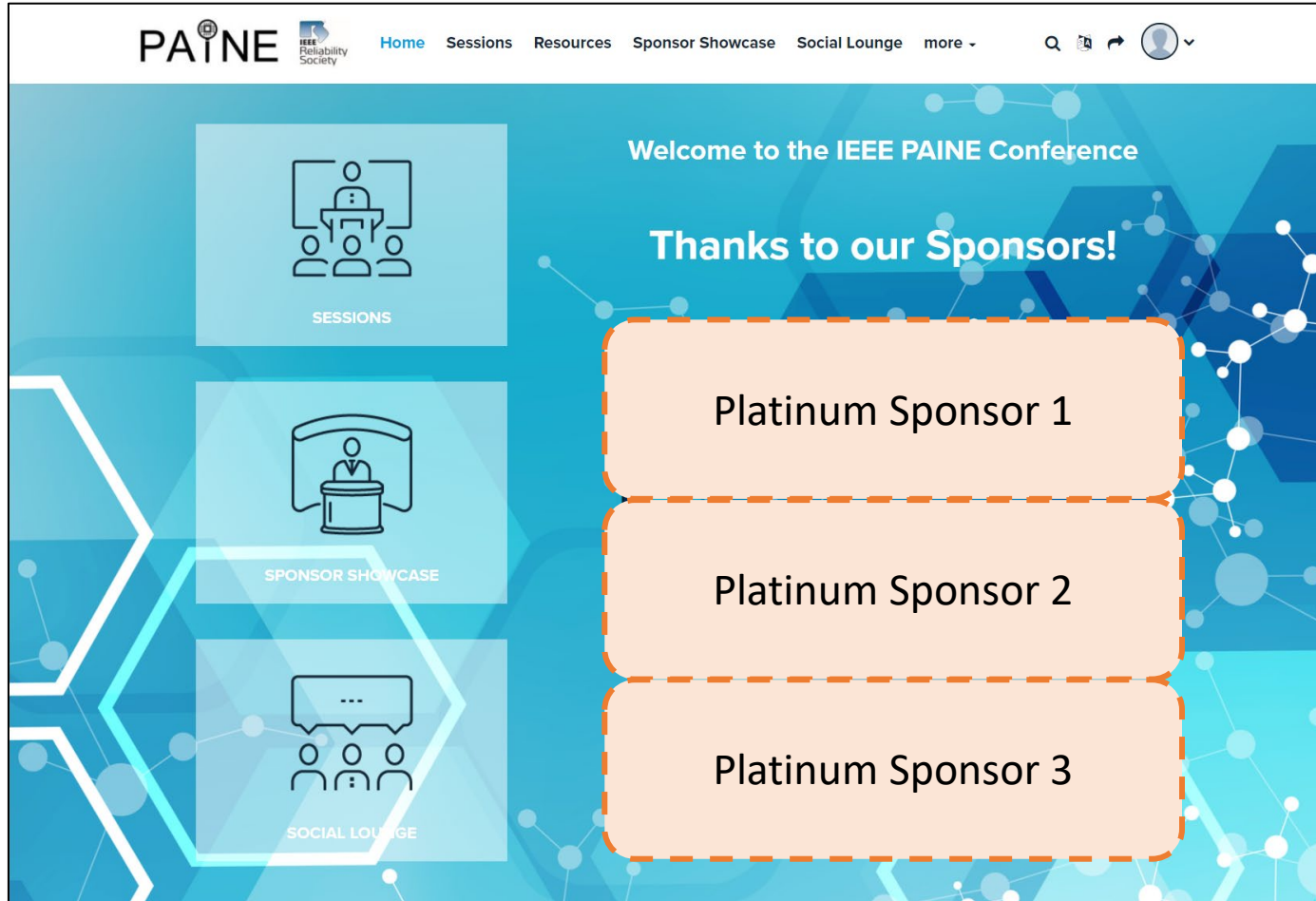
\$2,850

Combines your virtual exhibits booth with a Technical Session sponsorship. If you are an exhibitor and want to expand your visibility, this is the right choice for you. Steeply discounted to leverage your carry-over contributions from the last ECTC.

# Sponsorship Offering Overview



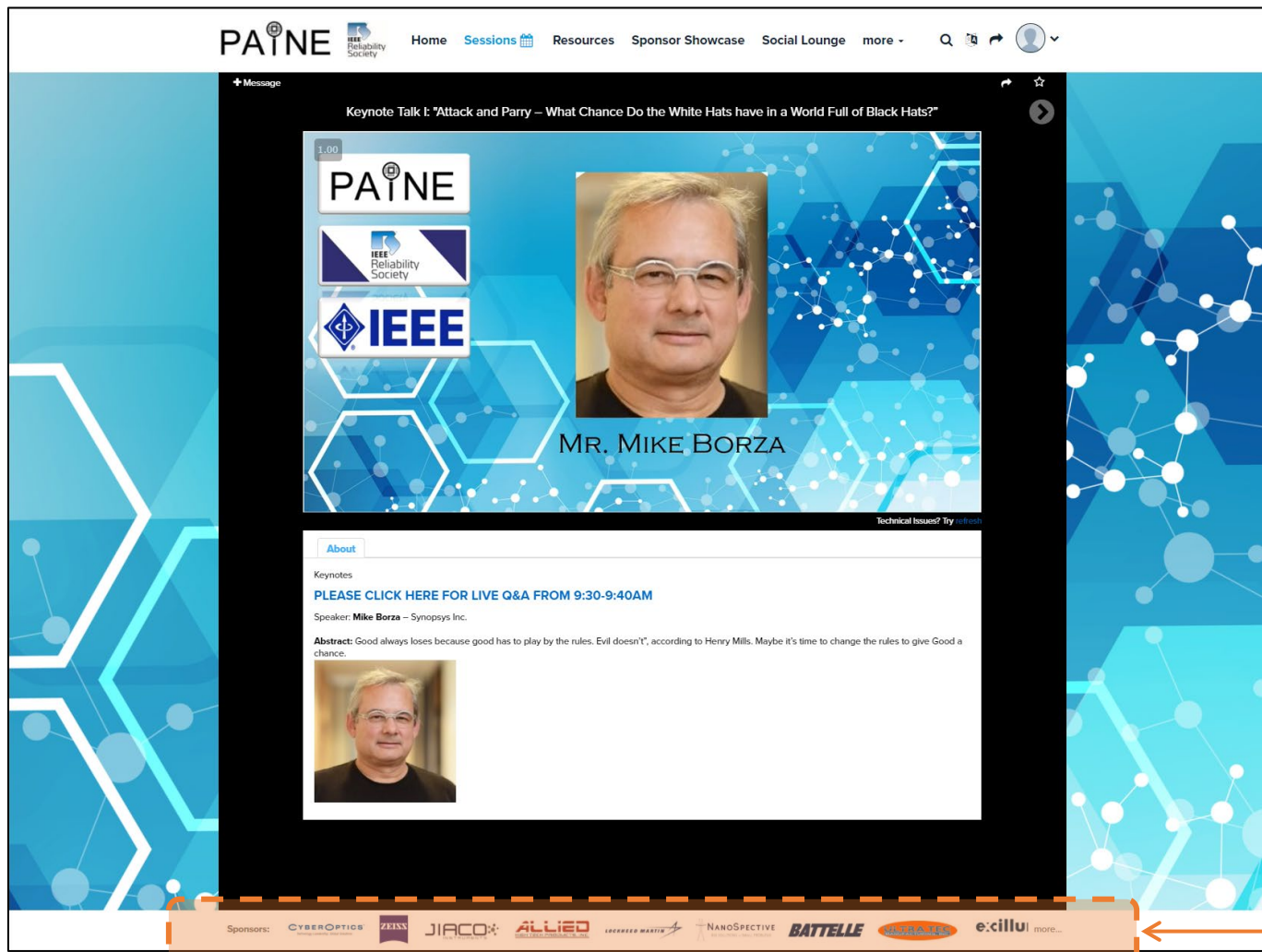
2021 ECTC Sponsorship Offering					
Sponsorship Level	Platinum	Gold	Panel Session	Technical Session	Exhibitor Combo
Price [\$k]	\$10	\$7.5	\$5	\$2.5	\$2.85
Available Sponsorships	3	5	10	46	46
<b>Sponsorship Details</b>					
Prominent display of your logo on Conference Home Page	Yes				
Logo at bottom banner of every page of conference	Yes	Yes			
Virtual Exhibit Booth (\$1,000 value)	1	1	1		1
Free Conference Registrations (\$360 value each)	4	2	1		1
Introduction to live and recorded Panel Session (your pre-recorded movie, 1 min)			Yes		
Introduction to Technical Session (your pre-recorded movie, 30 seconds)				Yes	Yes
Company logo on screen for 5 seconds between pre-recorded talks			Yes	Yes	Yes
Your announcement/Push Notification to online attendees before live session			2		
Recognition as Sponsor on ECTC web page and Conference Site	Yes	Yes	Yes	Yes	Yes
Recognition as Sponsor in eBlasts before and during conference	Yes	Yes	Yes	Yes	Yes
Recognition as Sponsor in Conference Program	Yes	Yes	Yes	Yes	Yes
Receive attendee list after the conference	Yes	Yes	Yes	Yes	Yes



Different conference (for illustrative purposes)

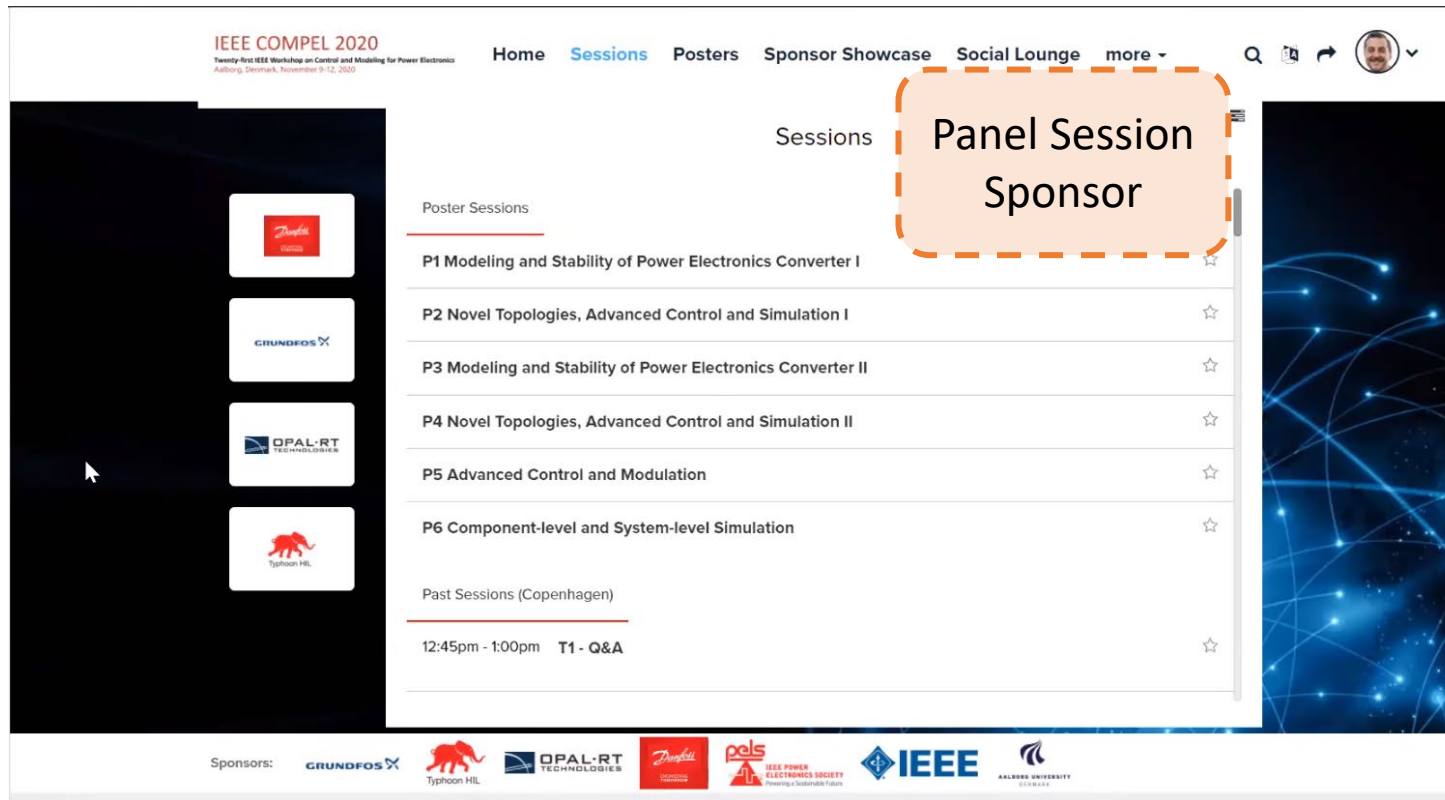
Name	Logo On Conference Home Page
Sponsorship	Platinum
Limit	3
Description	Company logo is prominently displayed on the conference home screen during the entire duration of the conference.

# Logo on bottom banner of every page of conference



Different conference (for illustrative purposes)

Name	Logo On Conference Home Page
Sponsorship	Platinum & Gold
Limit	8 (3 Platinum + 5 Gold)
Description	Company logo is displayed on bottom banner on every page of the entire conference.

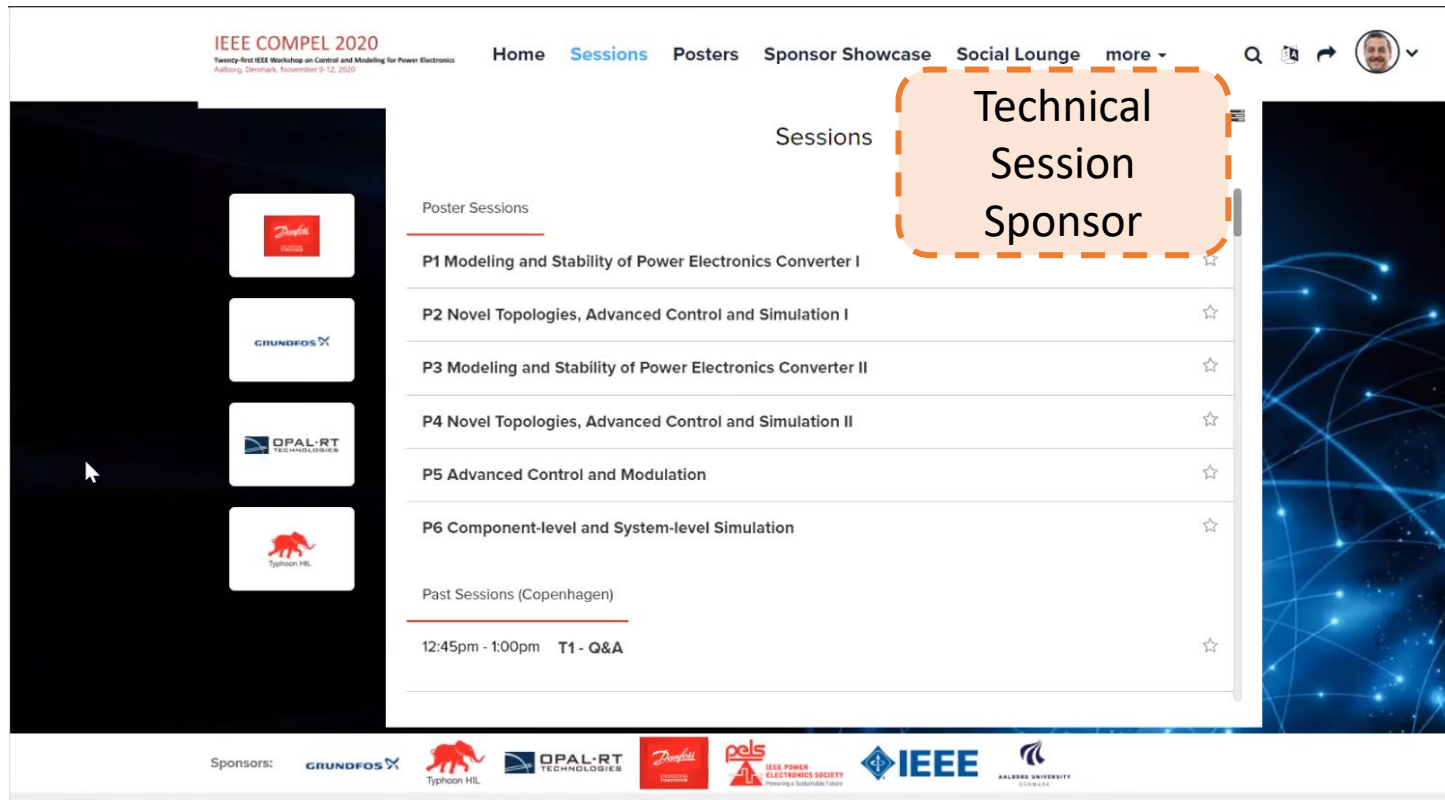


Different conference (for illustrative purposes)

Name	Panel Co-Host
Sponsorship	Panel Session Sponsor
Limit	10 (one for each session)
Description	<ul style="list-style-type: none"><li>• Your company logo next to the session in the online program</li><li>• Your logo on the session page</li><li>• Your one-minute introduction of the live panel session</li><li>• 2 push notifications to online attendees to announce the live session</li><li>• One free registration</li></ul>

Panel Session Overview: [Special Session PDF](#)

Link to available sessions (note that there are 2 tabs in the spreadsheet for Panel and Technical Sessions: [Panel Session List](#))



Different conference (for illustrative purposes)

Name	Session Co-Host
Sponsorship	Technical Session Sponsor
Limit	46 (one for each session)
Description	<ul style="list-style-type: none"><li>Your company logo next to the session in the online program</li><li>Your logo on the session page</li><li>Your 30-second introduction of the on-demand session</li></ul>

Technical Session Overview: [ECTC Program](#)

Link to available sessions (note that there are 2 tabs in the spreadsheet for Panel and Technical Sessions: [Technical Session List](#))



## • Panel Sessions:

- Market Trends & Geopolitical & Economic Outlook
- How Advanced Packaging Helped Develop Solutions to Respond to a Global Crisis
- Future Vision of Electronics Packaging – Industry Perspective
- Diversity Does Matter and Can Drive Enhanced Business Performance
- ECTC Young Professionals Meetup
- Latency: Are High-Bandwidth Optical Networks a Silver Bullet?
- Low Temperature Solder (LTS) – Packaging Challenges of a Next-Generation SMT Interconnect
- Pathogen Detection and Eradication
- Home Use Medical Devices and Packaging in Wearable Technologies
- Materials and Technologies for Advanced Packaging (5G, RF, Power, Harsh environment)

Technical Session Information can be found at:

<https://www.ectc.net/program/index.cfm>

**ECTC**  
2021 IEEE 71st Electronic Components and Technology Conference

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### Program

The following is the preliminary technical program for the 71st ECTC, this year a Virtual Conference. This program may undergo many changes, in the weeks and months to come, before evolving into the Final Program of the conference.

**TECHNICAL SESSIONS of the Virtual Event**  
*recorded presentations*

**Packaging Technologies**  
Session 1: 2D and 3D Chiplets Interconnects in FO-WLP/PLP  
Session 2: Wafer/Panel Level System Integration and Process Advances  
Session 3: Advanced Heterogeneous Chiplet and Integration for HPC  
Session 4: Heterogeneous Integration Using 2.xD/3D Packaging Technologies  
Session 5: Technologies for Advanced Substrates and Flip-Chip bonding  
Session 42: Topics in Advanced Packaging

**High-Speed, Wireless & Components**  
Session 26: Antenna-in-Package for 5G/6G and Radar Systems  
Session 27: Novel High-Frequency Integrated Modules and Systems  
Session 28: High-speed Signal Integrity and Interconnections  
Session 29: 3D Power Components and Power Integrity

**Emerging Technologies**  
Session 34: Flexible Hybrid Sensors and Electronics  
Session 35: Emerging Quantum and Advanced Interconnects  
Session 36: Packaging, Machine Learning, and Integration Technologies  
Session 45: Heterogeneous Integration, Flex and Emerging technologies

**Interconnections**  
Session 7: 3D TSV and Interposer  
Session 8: Chiplet Integration and Fan-Out Interconnections  
Session 9: Advances in Cu Bonding  
Session 10: Surface preparation for Cu bonding  
Session 11: Advanced Chip-to-Chip/Package Interconnections for 3D and Heterogeneous Integration  
Session 12: Flexible Interconnects and Low-Temperature Sintering  
Session 40: Materials and Techniques in High-Speed Interconnects

**Assembly & Manufacturing Technology**  
Session 23: Heterogeneous Integration processes and manufacturing  
Session 24: Fan-Out Wafer Level Packaging Developments and Applications  
Session 25: Advances in Assembly Methods  
Session 43: Manufacturing Techniques for Emerging Packaging Requirements

**Materials & Processing**  
Session 13: Dielectric materials for high-speed wireless communications  
Session 14: Enhancements in sintering technology and power applications



# Sponsor Exposure on ECTC & Conference Web Sites



Name	Recognition on Sponsors Page – Conference & ECTC
Sponsorship	All Sponsors
Limit	Available to all sponsors
Description	Company logo is displayed on the Sponsor page for both, the virtual event site, as well as ECTC home page.

*Thank  
you*



...for your continued support of:

2021 ECTC